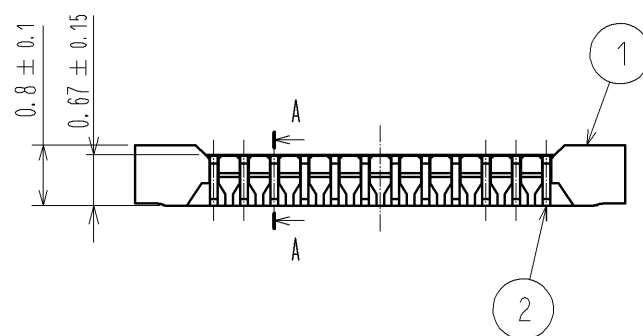
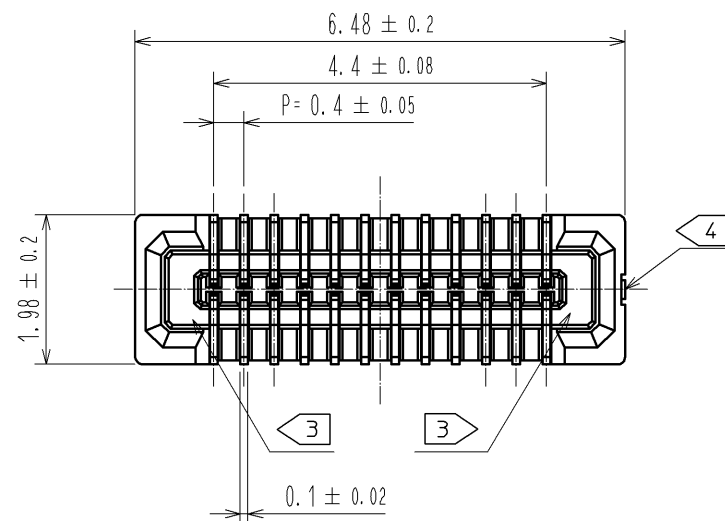
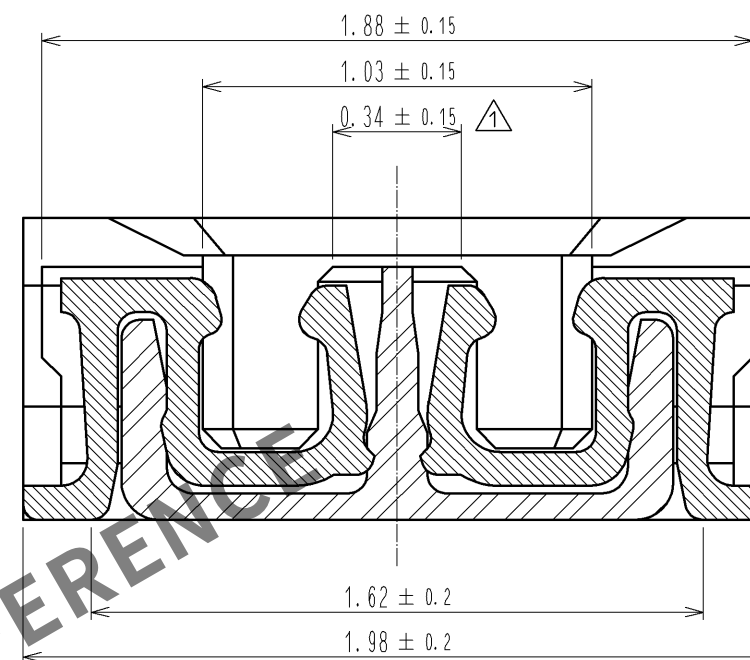


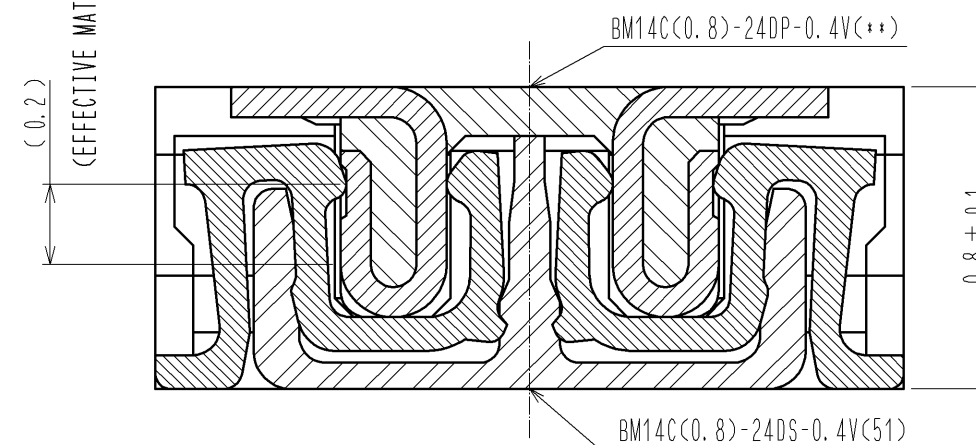


- NOTE) 1. ALL LEAD CO-PLANARITY SHALL BE 0.08mm MAX
2. CONTACT PLATING SPECIFICATIONS.
CONTACT AREA : GOLD 0.05 μ m MIN
SMT LEAD : GOLD 0.05 μ m MIN
UNDERPLATING : NICKEL 1 μ m MIN
(SURFACE : SEALING)
3. HRS MARK AND CAV NO. ARE INDICATED IN APPROX POSITION SHOWN.
4. GATE POSITION IS INDICATED IN APPROX POSITION SHOWN.

A-A (50:1)

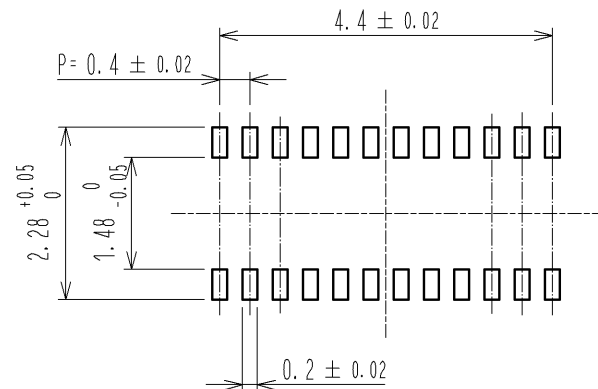


ENGAGEMENT FIGURE (50:1)



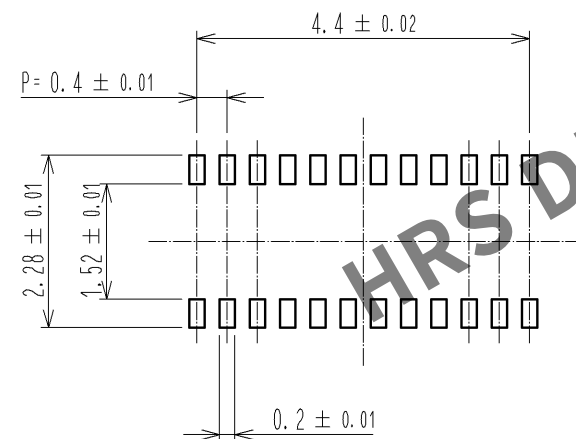
3	PS	CLEAR (ENBOSSED CARRIER TAPE)	6	PS	CLEAR (REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	2	5	PS	BLACK (PLASTIC REEL)
1	LCP	UL94 V-0, BLACK	4	POLYESTER	CLEAR (COVER TAPE)
NO.	MATERIAL	FINISH , REMARKS	NO.	MATERIAL	FINISH , REMARKS
UNITS mm		SCALE 10 : 1	COUNT 3	DESCRIPTION OF REVISIONS DIS-H-005556	DESIGNED YN. SAKAMOTO
HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA	09. 08. 28	DRAWING NO. EDC3-324407-01	DATE 11. 02. 25
		CHECKED : WR. FUKUCHI	09. 08. 28	PART NO. BM14C(0.8)-24DS-0.4V(51)	
		DESIGNED : TY. OOI	09. 08. 28	CODE NO. CL684-8018-2-51	
		DRAWN : YN. SAKAMOTO	10. 12. 24		

◆ RECOMMENDED PCB LAYOUT

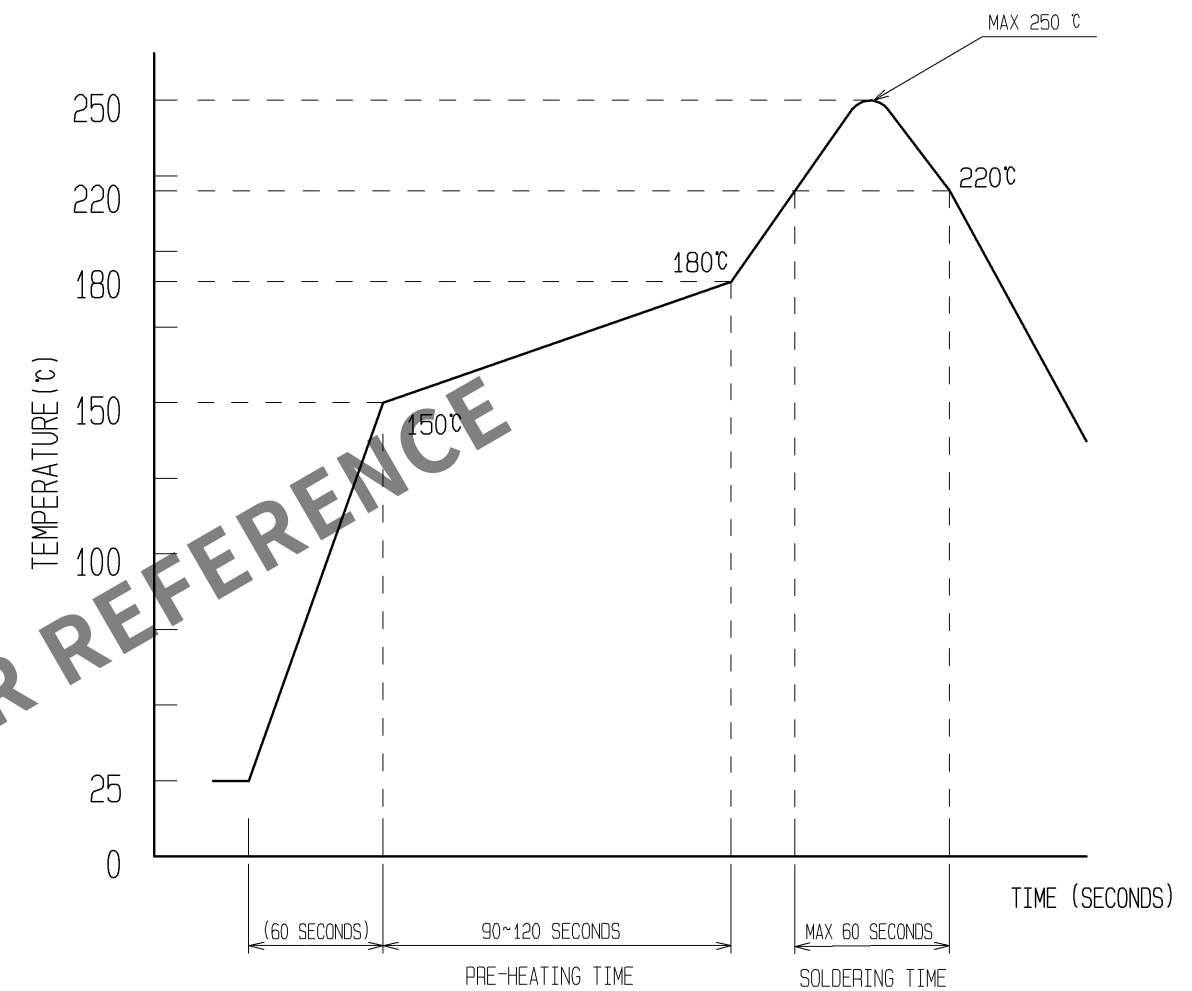


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 100 μ m



5 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.



- REFLOW METHOD: IR REFLOW
NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
- 1) REFLOW TIME
DURATION ABOVE 220 $^{\circ}$ C, 60 SEC. MAX.
(PEAK TEMPERATURE: 250 $^{\circ}$ C MAX)
 - 2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150 $^{\circ}$ C
PRE-HEAT TEMPERATURE(MAX): 180 $^{\circ}$ C
PRE-HEAT TIME: 90-120 sec.

5 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND
OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE, THEREFORE,
A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED
PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-324407-01
PART NO.	BM14C(0.8)-24DS-0.4V(51)
CODE NO.	CL684-8018-2-51

1/2/3

